

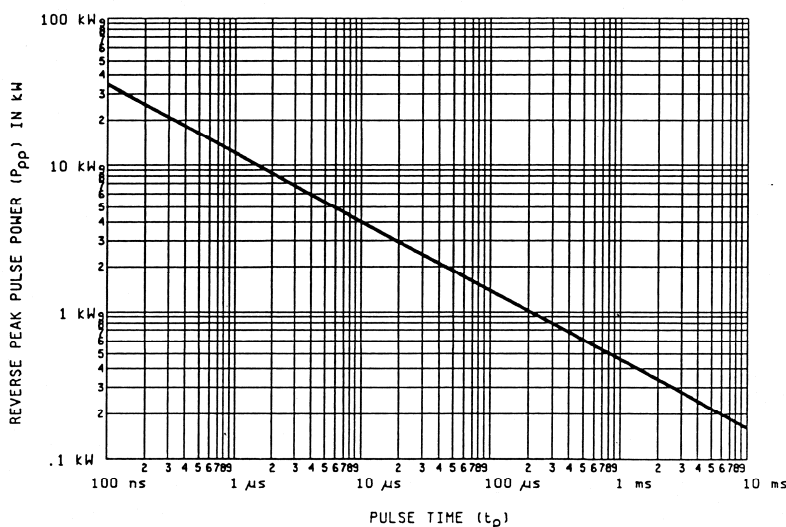
**ELECTRICAL CHARACTERISTICS**

TYPE	BREAK DOWN VOLTAGE V(BR) MIN.	BREAKDOWN CURRENT I <sub>(BR)</sub>	WORKING PEAK VOLTAGE V <sub>WM</sub>	MAX LEAKAGE CURRENT I <sub>D</sub>	MAXIMUM CLAMPING VOLTAGE V <sub>C</sub> @ 10/1000 μs	MAXIMUM PEAK PULSE CURRENT I <sub>PP</sub>		MAXIMUM TEMP. COEF. OF V(BR)
						@8/20 μs	@10/1000 μs	
	Volts	mAdc	Vdc	μAdc	V(pk)	A(pk)	A(pk)	%/°C
1N6461US	5.6	25	5	3000	9.0	315	56	-.03, +0.04
1N6462US	6.5	20	6	2500	11.0	258	46	0.06
1N6463US	13.6	5	12	500	22.6	125	22	0.085
1N6464US	16.4	5	15	500	26.5	107	19	0.085
1N6465US	27.0	2	24	50	41.4	69	12	.096
1N6466US	33.0	1	30.5	3	47.5	63	11	.098
1N6467US	43.7	1	40.3	2	63.5	45	8	.101
1N6468US	54.0	1	51.6	2	78.5	35	6	.103

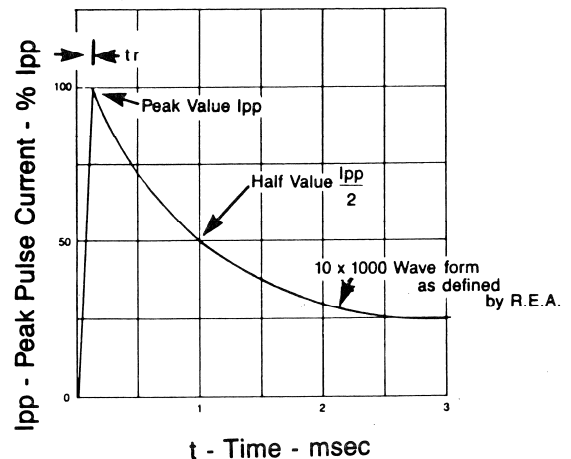
**SYMBOLS & DEFINITIONS**

Symbol	Definition
V <sub>BR</sub>	Minimum Breakdown Voltage: The minimum voltage the device will exhibit at a specified current.
V <sub>WM</sub>	Working Peak Voltage: The maximum peak voltage that can be applied over the operating temperature range. This is also referred to as Standoff Voltage.
I <sub>D</sub>	Maximum Standoff Current: The maximum current that will flow at the specified voltage and temperature.
V <sub>C</sub>	Maximum clamping voltage at specified I <sub>PP</sub> (Peak Pulse Current) at the specified pulse conditions.
P <sub>PP</sub>	Peak Pulse Power: The peak power dissipation resulting from the peak impulse current I <sub>PP</sub> .

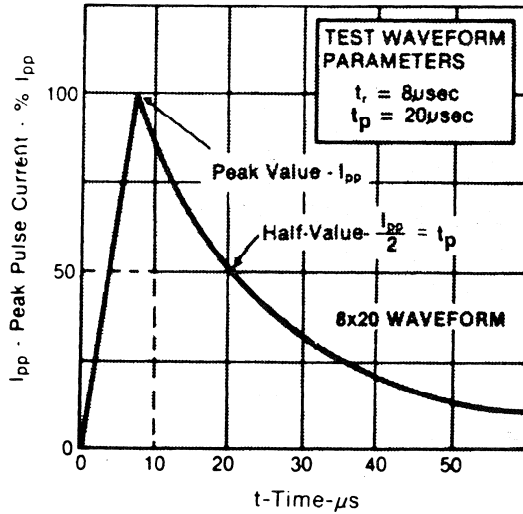
**GRAPHS**



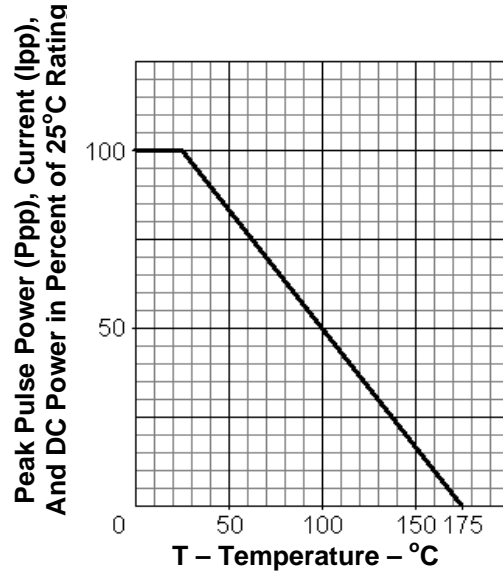
**FIGURE 1**  
PEAK PULSE POWER vs. PULSE TIME



**FIGURE 2**  
10/1000 μs CURRENT IMPULSE WAVEFORM

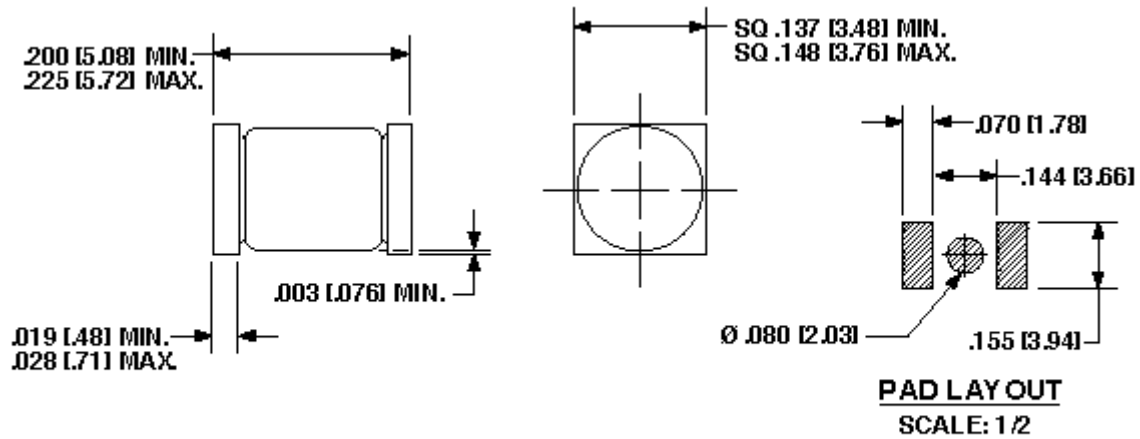


**FIGURE 3**  
8/20  $\mu$ s CURRENT IMPULSE WAVEFORM  
(per MIL-PRF-19500/551)



**FIGURE 4**  
DERATING CURVE

PACKAGE DIMENSIONS Inches [mm]



NOTE: DIMENSIONS IN INCHES [MM]

**E-MELF-PKG (D-5B)**

**Note:** If mounting requires adhesive separate from the solder, an additional 0.080 inch diameter contact may be placed in the center between the pads as an optional spot for cement as shown in the pad layout.